


MATERIAL DECLARATION SHEET



Material Number	PTVS3-015C-TH			
Product Line	Semiconductor Products			
Compliance Date	November 18 2015			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.164000	Bisphenol Copolymer	25036-25-3	60.00	8.37	13.95
				Alumina Trihydrate	21645-51-2	15.00	2.09	
				Fused silica	60676-86-0	20.00	2.79	
				Hydrated Iron Oxide	20344-49-4	1.50	0.21	
				Titanium Dioxide	13463-67-7	1.50	0.21	
				Melamine Cyanurate	37640-57-6	1.50	0.21	
				Amine Adduct	trade secret	0.50	0.07	
2	Electrodes	Copper	0.404000	Copper	7440-50-8	99.10	34.05	34.36
				Silver	7440-22-4	0.40	0.14	
				Other, not to declare	-	0.50	0.17	
3	Terminations	Copper	0.516451	Copper	7440-50-8	99.50	43.70	43.92
				Other, not to declare	-	0.50	0.22	
4	Termination Finish	Silver	0.003549	Silver	7440-22-4	100.00	0.30	0.30
5	Chip	Silicon Die	0.023100	Silicon	7440-21-3	85.34	1.67	1.96
				Aluminium	7429-90-5	5.13	0.10	
				Nickel	7440-02-0	9.09	0.18	
				Gold	7440-57-5	0.44	0.01	
6	Die Attach	Solder	0.030845	Lead*	7439-92-1	92.50	2.42	2.62
				Tin	7440-31-5	5.00	0.13	
				Silver	7440-22-4	2.50	0.07	
7	Die Coating	Silicone	0.034000	Polysiloxane	63148-62-9	22.11	0.64	2.89
				Chromium Sesquioxide	1308-38-9	5.67	0.16	
				Fumed Silica	112945-52-5	11.11	0.32	
				Filler	trade secret	61.11	1.77	
Total weight			1.175945					

This Document was updated on: 2015/11/18

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)